Switch-mode **Soft Ultrafast Recovery Power Rectifier**

Plastic DPAK Package

MSRD620CT, NRVSRD620VCT, SSRD8620CT Series

State-of-the-art geometry features epitaxial construction with glass passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies, free wheeling diode and polarity protection diodes.

Features

- Soft Ultrafast Recovery (35 ns typ)
- Highly Stable Oxide Passivated Junction
- Matched Dual Die Construction May Be Paralleled for High Current Output
- Short Heat Sink Tab Manufactured Not Sheared
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- NRVSRD and SSRD8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
 - ♦ Machine Model = C
 - ♦ Human Body Model = 2



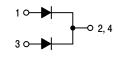
ON Semiconductor®

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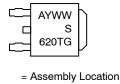
SOFT ULTRAFAST RECTIFIER 6.0 AMPERES, 200 VOLTS

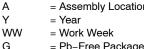


DPAK CASE 369C



MARKING DIAGRAM





= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MSRD620CTG	DPAK (Pb-Free)	75 Units/Rail
MSRD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVSRD620VCTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SSRD8620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (T _C = 137°C)	Ι _Ο		A
Per Leg Per Package		3.0 6.0	
Peak Repetitive Forward Current (Square Wave, Duty = 0.5, T _C = 138°C)	I _{FRM}		A
Per Leg		6.0	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}		A
Per Package		50	
Storage / Operating Case Temperature	T _{stg,} T _c	–55 to +175	°C
Operating Junction Temperature	TJ	–55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

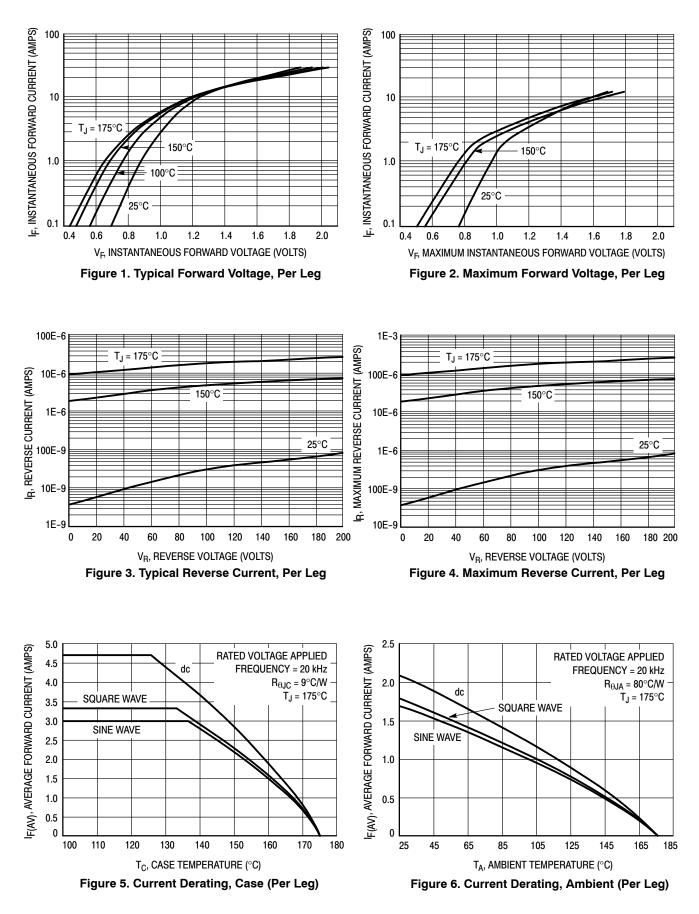
THERMAL CHARACTERISTICS

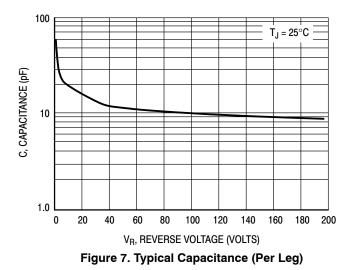
Rating	Symbol	Value	Unit
Thermal Resistance - Junction-to-Case	$R_{\theta JC}$		°C/W
Per Leg		9.0	
Thermal Resistance – Junction-to-Ambient	$R_{\theta JA}$		°C/W
Per Leg		80	

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Va	lue	Unit
Maximum Instantaneous Forward Voltage (Note 1) (See Figure 2) Per Leg	V _F	T _J = 25°C	T _J = 150°C	V
(I _F = 3.0 A) (I _F = 6.0 A)		1.15 1.35	1.05 1.30	
Maximum Instantaneous Reverse Current (See Figure 4) Per Leg	I _R	T _J = 25°C	T _J = 150°C	μΑ
(V _R = 200 V) (V _R = 100 V)		5.0 2.0	200 100	
Maximum Reverse Recovery Time (Note 2) Per Leg (V _R = 30 V, I _F = 1.0 A, di/dt = 50 A/μs) (V _R = 30 V, I _F = 3.0 A, di/dt = 50 A/μs)	t _{rr}		.5 :5	ns
Maximum Peak Reverse Recovery Current Per Leg (V _R = 30 V, I _F = 1.0 A, di/dt = 50 A/μs) (V _R = 30 V, I _F = 3.0 A, di/dt = 50 A/μs)	I _{RM}		.0 .0	A

1. Pulse Test: Pulse Width \leq 250 $\mu s,$ Duty Cycle \leq 2%. 2. t_{rr} measured projecting from 25% of I_{RM} to ground.





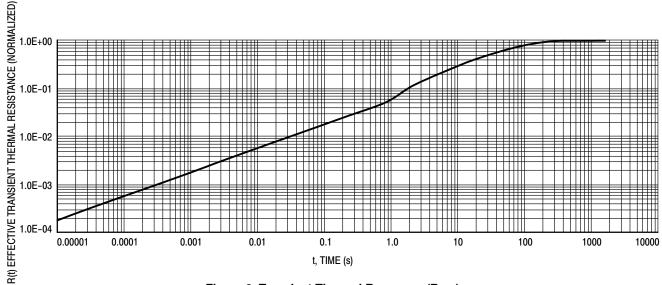


Figure 8. Transient Thermal Response ($R_{\theta JA}$)

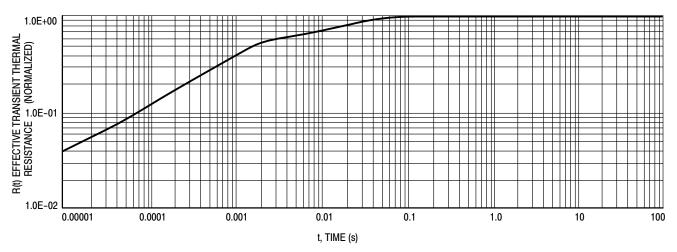
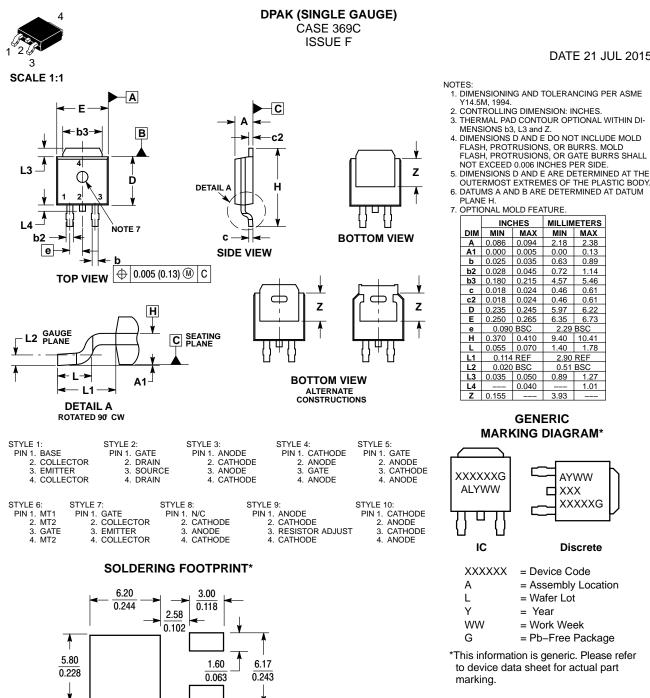


Figure 9. Transient Thermal Response ($R_{\theta JC}$)





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DPAK SINGLE GAUGE SURFACE MOUNT		PAGE 1 OF 2	

 $\left(\frac{\text{mm}}{\text{inches}}\right)$

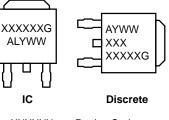
SCALE 3:1

DATE 21 JUL 2015

- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE

OPTIONAL MOLD FEATURE.				
	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90	REF
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

MARKING DIAGRAM*



XXXXXX	= Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
WW	= Work Week
G	= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part





PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY L. GAN	24 SEP 2001
А	ADDED STYLE 8. REQ. BY S. ALLEN.	06 AUG 2008
В	ADDED STYLE 9. REQ. BY D. WARNER.	16 JAN 2009
С	ADDED STYLE 10. REQ. BY S. ALLEN.	09 JUN 2009
D	RELABELED DRAWING TO JEDEC STANDARDS. ADDED SIDE VIEW DETAIL A. CORRECTED MARKING INFORMATION. REQ. BY D. TRUHITTE.	29 JUN 2010
E	ADDED ALTERNATE CONSTRUCTION BOTTOM VIEW. MODIFIED DIMENSIONS b2 AND L1. CORRECTED MARKING DIAGRAM FOR DISCRETE. REQ. BY I. CAM-BALIZA.	06 FEB 2014
F	ADDED SECOND ALTERNATE CONSTRUCTION BOTTOM VIEW. REQ. BY K. MUSTAFA.	21 JUL 2015

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